



ISO 9001-2015 Certified

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TECHNICAL BULLETIN

STG-41

Silicone Thermal Compound

Product Description

STG-41 is a non-reactive, Silicone, Thermally Conductive Grease with a high thermal conductivity and low thermal resistance with a soft, non-flowable consistency. This product is formulated with specialty binding agents to achieve lowest amount of bleed and evaporations. It is designed for applications where a silicone thermal interface material is required and where the device may later need to be easily removed from the heat sink. This compound is ideally suited for use in thin cross-sectional thicknesses down to ≤ 1 mil.

Key Features and Benefits

• Good Thermal Performance- (2.0 W/m ² k)
• Low Interface Thermal Resistance. – (0.05 °C-In ² /W)
• Thin Bond lines to ≤ 1 mil.
• Low bleed and evaporation.

- Non-Toxic.
- Reworkable/Easy to Remove.
- Easy to Apply by Dispensing or Screen Printing/Stencil.

Typical Applications

STG-41 Heat Sink Compound is applied to the base and mounting studs of transistors, diodes and silicone controlled rectifiers. In these situations, a small amount of the thermal grease is applied using either the dispensing of screen printing/stencil methods **STG-41** can be used as a high-voltage corona suppressant/non-flammable coating, in connections for fly back transformers located in TV sets and similar design applications. It is also used in mounting semiconductor devices; thermoelectric modules; power transistors and diodes; coupling entire heat generating assemblies to chassis; heat transfer medium on ballasts; thermal joints; thermocouple wells; mounting power resistors; and for any devices where efficient cooling is required in major industries including, electronic (computer, appliance, wireless, etc.), automotive and electrical.

Shelf-Life

STG-41 has a shelf-life of 5 years at room temperature (25°C) in unopened containers. Slight settling of the filler may occur during long-term storage. In this case, it is recommended to re-disperse the filler by hand or mechanical mixing. Refrigerate material at 0-10°C to avoid any settling.

Clean Up

Standard approved clean-up and disposal procedures should be followed in every situation. The use of disposable containers and utensils are recommended whenever possible to simplify and expedite clean-up. However, when disposable containers are impractical, **STG-41** can be removed by cleaning solvents with such as Mineral Spirit (Paint Thinner), Heptane or Isopropyl Alcohol.

Typical Properties

Property	Value
Viscosity:	Thixotropic Paste
Specific Gravity, @ 25°C	2.5
Color:	White
Evaporation, @ 200°C, 24 Hrs., %/Wt.	0.5
Bleed @ 200°C, 24 Hrs., %/Wt.	0.4
Thermal Conductivity, (ASTM D5470)	
BTU.In/(Hr.Ft ² .°F)	13.8
W/m.²K	2.0
Thermal Resistance (°C-In²/W)	0.05
Electrical Properties:	390
Dielectric strength (ASTM D150) 0.05" gap, V/mil	
Dielectric constant (ASTM D150) 25°C @ 1,000 Hz.	4.40
Dissipation factor (ASTM D150) 25°C @ 1,000 Hz.	0.0021
Volume Resistivity (ASTM D257) Ohm-cm.	2.8 x 10 ¹⁴
Operating Temperature Range	-50°C to 200°C

CLAIMER: All data given here is offered as a guide to the use of these materials and not as a guarantee of their performance. The user should evaluate their suitability for own purposes. Properties are typical and should not be used in preparing specifications. Statements are not to be construed as recommendations to infringe any patent.